MicroThin™

Introduction

MicroThin™ is a very low profile 3µm or 5µm copper foil with an 18µm or 35µm copper peelable carrier for high-density circuit applications. The releasing layer can be peeled-off after lamination and recycled.

Benefits

- Enables very fine circuit pattern production
- Easy to release carrier after high temperature lamination
- Even thickness of the thin foil
- Adequate peel strength

Product	Copper Thickness	Copper Foil	Carrier Thickness
MicroThin™	5 microns 3 microns	VLP	18 microns 35 microns

Properties	Unit	12µm *	18µm *	35µm *
Peel Strength B at room Temp	lbs/in	10	10	10
S4 (260°C x 20 sec)	lbs/in	7.5	10.5	15

* 3µm MicroThin™ foil after plating up to 12µm, 18µm, 35µm

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